

March/April	May/June	July/August	September/October	November / December
Ad Closing 2018/02/20	2018/04/20	2018/06/20	2018/08/20	2018/10/20
Material Due 2018/02/25	2018/04/25	2018/06/25	2018/08/25	2018/10/25
Mailing Date 2018/03/01	2018/05/01	2018/07/01	2018/09/01	2018/11/01
Year Book 2018		Smart Manufacturing		
Industry Outlook 产业展望	MES 制造执行系统	Intelligent Robot 智能机器人	Material Tracking 物料追踪	Smart Factory 智慧工厂
Tech Investment		Compound Semiconductor		
SIIP 中国半导体与 世界互动的平台	GaN Devices GaN 器件	GaAs Devices GaAs 器件	SiC Devices SiC 器件	5G Technologies 5G 技术
Wafer Fabrication				
Fabs Facilities 工厂设施	Interconnects and Yield Improvement 互连和成品率提升	Wafer Cleaning Technology 晶圆清洗技术	IoT IC Process IoT IC 工艺	CMP Processing CMP 工艺
Packaging & Testing				
SEMICON China Special Issue	SiP Packaging 系统级封装	Wafer-Level Package 晶圆级封装	New Electronic Assembly 电子组装封装新技术	Test and measurement 测试与测量
e-Newsletter				
SEMI China Daily News		IC APP;	eCarChina;	Show Daily during the SEMICON China

AD.Type	Dimension width*height(mm)	File size	Format	1x(\$)	3x(\$)	5x(\$)
1	Full Page 200*267	>300dpi	JPEG / PDF / EPS	3,200	2,600	2,000
2	1/2 Page 200*134 (horz.,vert.,or island)	>300dpi	JPEG / PDF / EPS	1,920	1,560	1,200
3	Cover Two Spread 400*267 (inside front cover and page 1)	>300dpi	JPEG / PDF / EPS	7,000	5,600	4,300
4	Cover Two 200*267 (inside front cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
5	Cover Three 200*267 (inside back cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
6	Cover Four 200*267 (back cover)	>300dpi	JPEG / PDF / EPS	4,900	4,000	3,000

* Please allow 3mm bleeds. Color model: CMYK

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